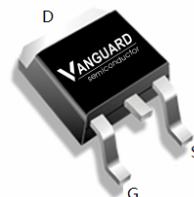


Features

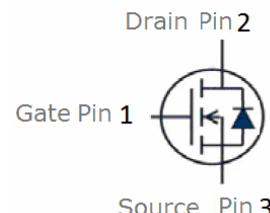
- N-Channel
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=4.5\text{ V}$
- Fast Switching
- Pb-free lead plating; RoHS compliant

V_{DS}	100	V
$R_{DS(on),TYP} @ V_{GS}=10\text{V}$	150	$\text{m}\Omega$
$R_{DS(on),TYP} @ V_{GS}=4.5\text{ V}$	165	$\text{m}\Omega$
I_D	8	A

TO-252



Part ID	Package Type	Marking	Tape and reel information
VSD160N10MS	TO-252	160N10	2500pcs/Reel



Maximum ratings, at $T_j=25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	100	V
I_s	Diode continuous forward current	$T_c=25^\circ\text{C}$	A
I_D	Continuous drain current@ $V_{GS}=10\text{V}$	$T_c=25^\circ\text{C}$	A
		$T_A=70^\circ\text{C}$	A
I_{DM}	Pulse drain current tested ①	$T_c=25^\circ\text{C}$	A
EAS	Avalanche energy, single pulsed ②	$I_D=4\text{A}$	mJ
P_D	Maximum power dissipation	$T_A=25^\circ\text{C}$	W
V_{GS}	Gate-Source voltage	± 20	V
$T_{STG} T_J$	Storage and operating temperature range	-55 to 175	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	7.5	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	60	°C/W

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 16\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 10	μA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	2.0	3.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=5\text{A}$	--	150	160	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=3\text{A}$	--	165	180	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	405	--	pF
C_{oss}	Output Capacitance		--	36	--	pF
C_{rss}	Reverse Transfer Capacitance		--	18	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=1\text{A}, V_{\text{GS}}=10\text{V}$	--	9	--	nC
Q_{gs}	Gate-Source Charge		--	1.5	--	nC
Q_{gd}	Gate-Drain Charge		--	2.1	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=30\text{V}, I_{\text{D}}=1\text{A}, R_{\text{G}}=6.8\Omega, V_{\text{GS}}=10\text{V}$	--	9	--	nS
t_r	Turn-on Rise Time		--	8.1	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	20	--	nS
t_f	Turn-Off Fall Time		--	13.5	--	nS
Source- Drain Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{sd}}=2.5\text{A}, V_{\text{GS}}=0\text{V}$	--	0.81	1.3	V
t_{rr}	Reverse Recovery Time	$T_J=25^\circ\text{C}, I_{\text{sd}}=1.5\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$	--	25	--	nS
Q_{rr}	Reverse Recovery Charge		--	31	--	nC

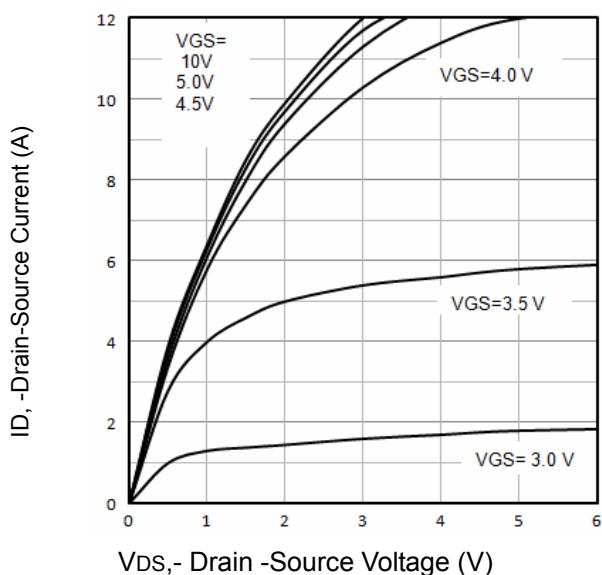
NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.3\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 4\text{A}$, $V_{GS} = 10\text{V}$. Part not recommended for use above this value

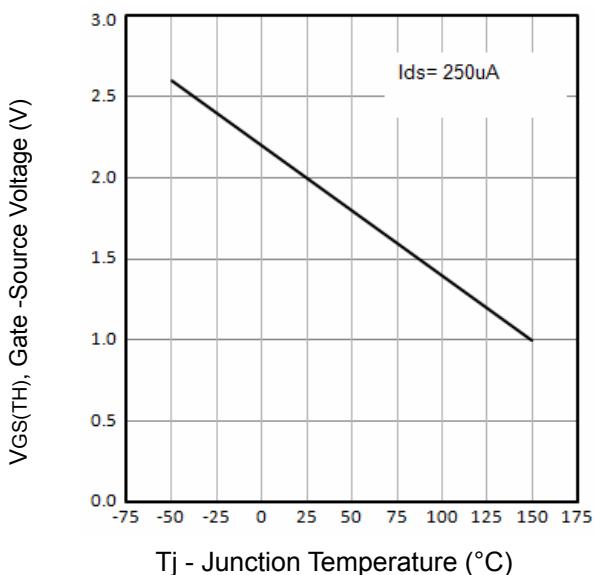
③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Typical Characteristics



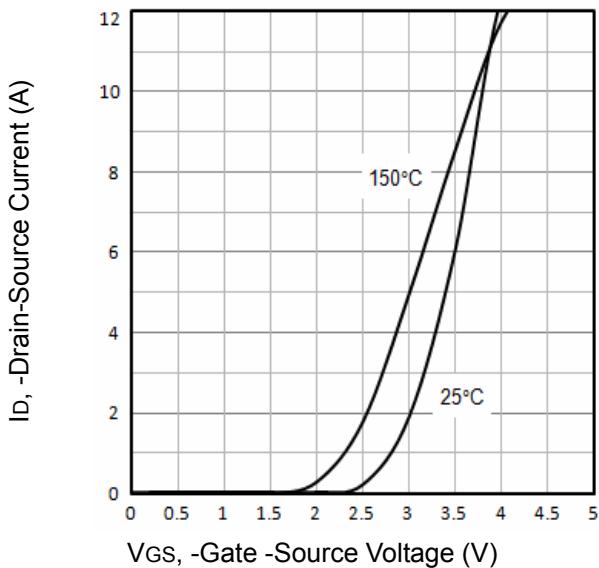
V_{DS}, - Drain -Source Voltage (V)

Fig1. Typical Output Characteristics



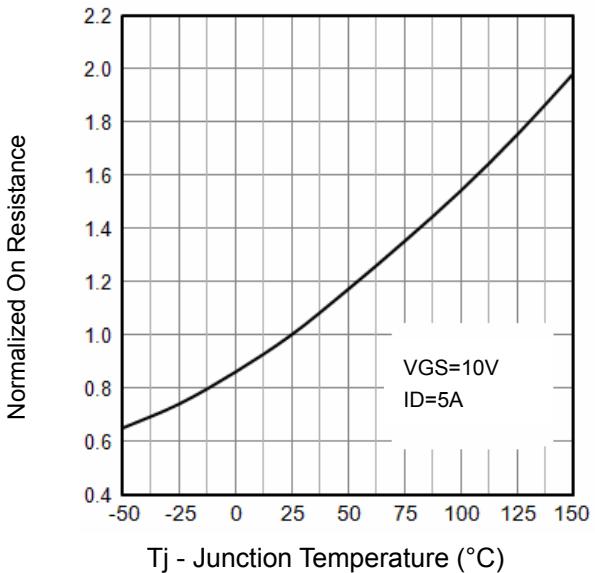
T_j - Junction Temperature (°C)

Fig2. Threshold Voltage Vs. Temperature



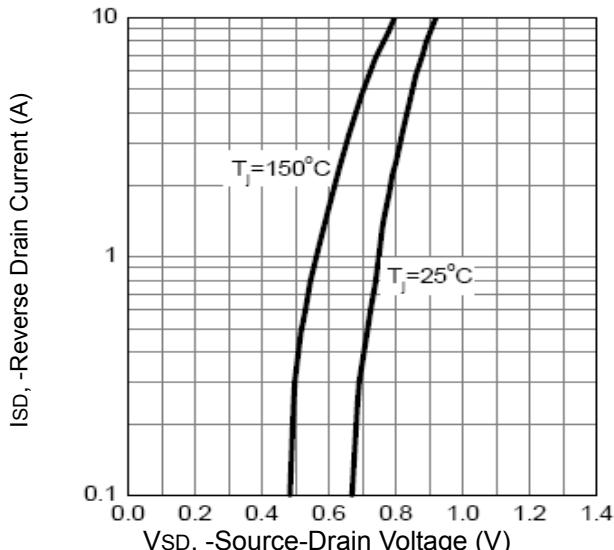
V_{GS}, -Gate -Source Voltage (V)

Fig3. Typical Transfer Characteristics



T_j - Junction Temperature (°C)

Fig4. Normalized On-Resistance Vs. Temperature



V_{SD}, -Source-Drain Voltage (V)

Fig5. Typical Source-Drain Diode Forward Voltage

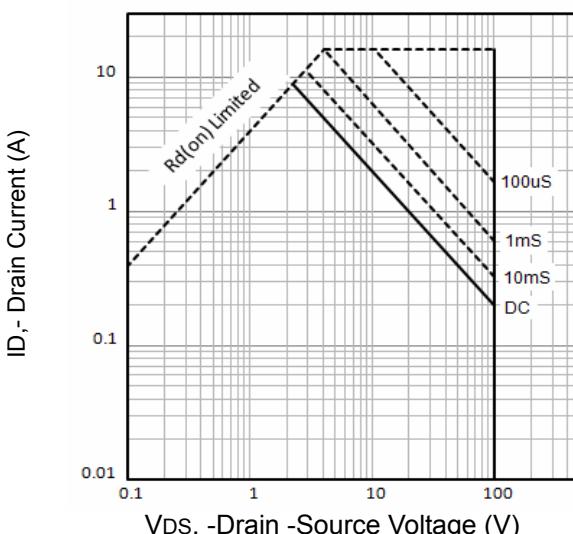


Fig6. Maximum Safe Operating Area

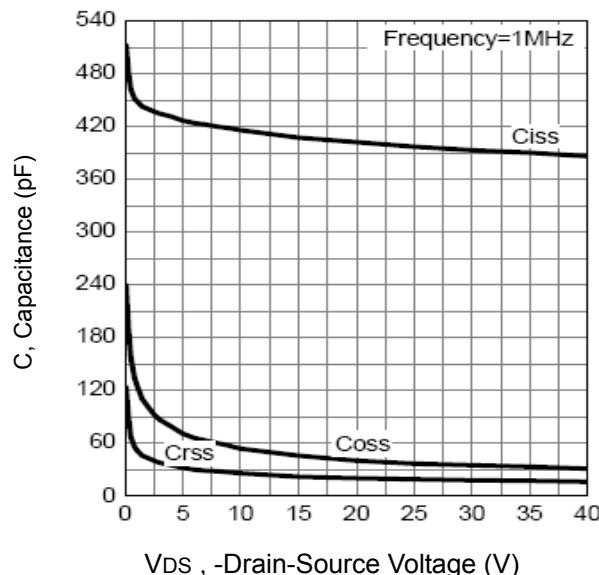


Fig7. Typical Capacitance Vs.Drain-Source Voltage

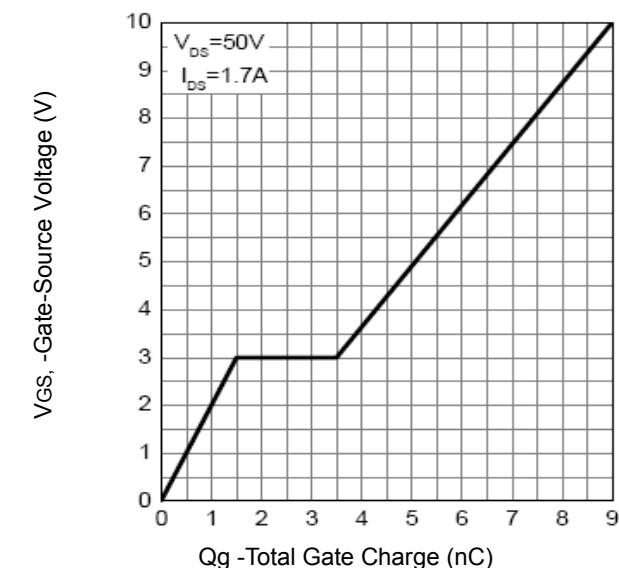


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

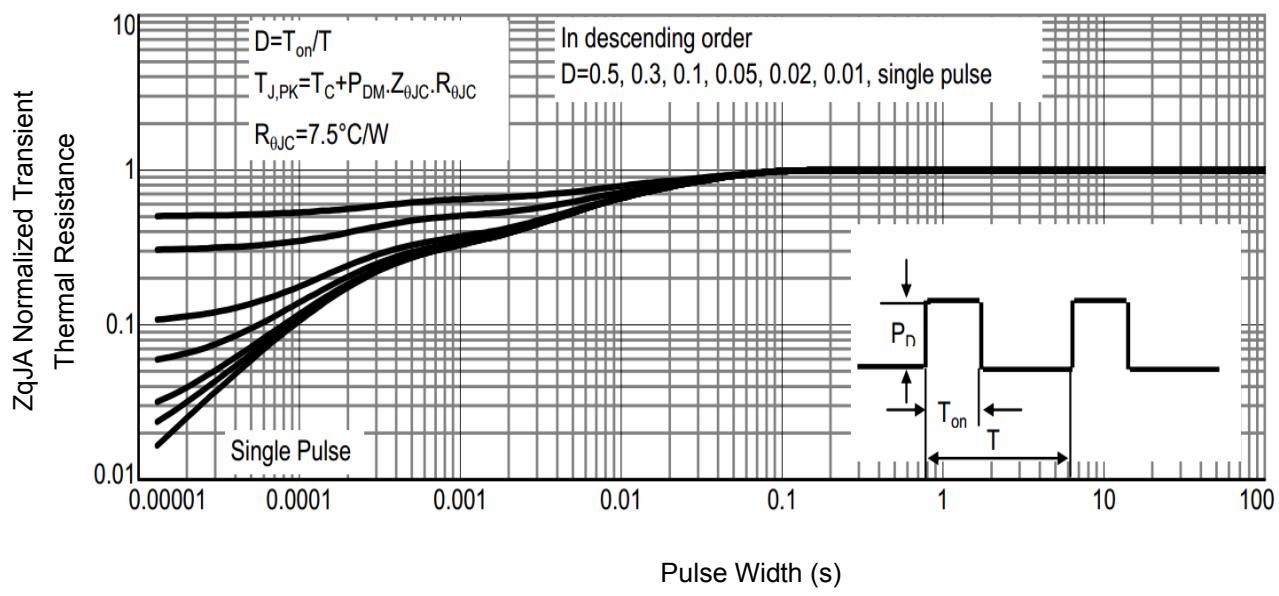


Figure 9: Normalized Maximum Transient Thermal

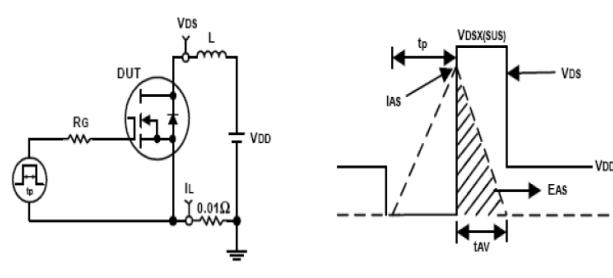


Fig10. Unclamped Inductive Test Circuit and Waveforms

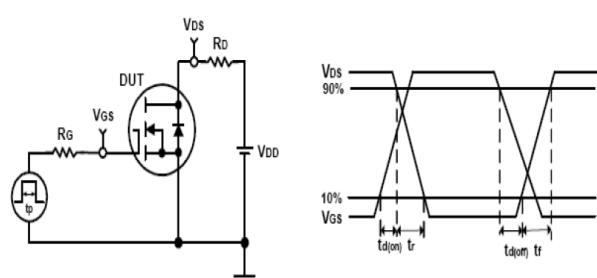
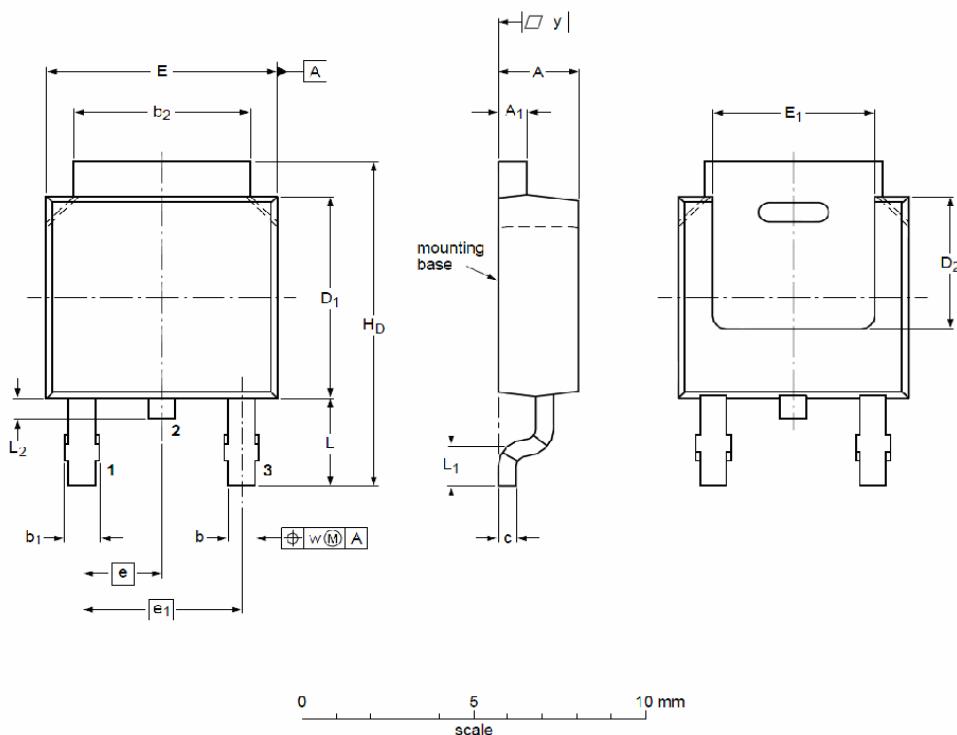


Fig11. Switching Time Test Circuit and waveforms

TO-252 Package Outline



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.22	2.30	2.38	A ₁	0.46	0.58	0.93
b	0.71	0.79	0.89	b ₁	0.90	0.98	1.10
b ₂	5.00	5.30	5.46	c	0.20	0.40	0.56
D ₁	5.98	6.05	6.22	D ₂	--	4.00	--
E	6.47	6.60	6.73	E ₁	5.10	5.28	5.45
e	--	2.28	--	e ₁	--	4.57	--
H _D	9.60	10.08	10.40	L	2.75	2.95	3.05
L ₁	--	0.50	--	L ₂	0.80	0.90	1.10
w	--	0.20	--	y	0.20	--	--

Customer Service

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